

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUZ30N10S5L240	**Issued**	7. January 2020
MA#	MA005346527		
Package	PG-TSDSON-8-32	**Weight***	35.36 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.346	0.98	0.98	9786	9786
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88	
	non noble metal	zinc	7440-66-6	0.012	0.04		352	
	non noble metal	iron	7439-89-6	0.249	0.70		7037	
	non noble metal	copper	7440-50-8	10.102	28.57	29.32	285725	293202
wire	noble metal	gold	7440-57-5	0.027	0.08	0.08	768	768
encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1053	
	plastics	epoxy resin	-	1.917	5.42		54220	
	inorganic material	silicondioxide	60676-86-0	16.658	47.11	52.64	471135	526408
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11321	11321
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2422	2422
solder	non noble metal	tin	7440-31-5	0.011	0.03		298	
	noble metal	silver	7440-22-4	0.013	0.04		372	
	non noble metal	lead	7439-92-1	0.503	1.42	1.49	14218	14888
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2060	
	non noble metal	copper	7440-50-8	2.958	8.36	8.58	83650	85839
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17	
	non noble metal	zinc	7440-66-6	0.002	0.01		66	
	non noble metal	iron	7439-89-6	0.047	0.13		1329	
	non noble metal	copper	7440-50-8	1.908	5.40	5.54	53954	55366
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com